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| PTO-1449 | Application No. | Applicant(s) |
| | To be Assigned 10/659181 | Howard, et al. |
| Information Disclosure Citation In an Application | Docket Number | Group Art Unit |
| | TI-36332 (032350.B531) | To be Assigned 2815 |
| | Filing Date | Sept. 10, 2003 |

U.S. PATENT DOCUMENTS

| | DOCUMENT NO. | DATE | NAME | CLASS | SUBCLASS | FILING DATE |
|---|--------------|------|------|-------|----------|-------------|
| A | | | | | | |
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FOREIGN PATENT DOCUMENTS

| | DOCUMENT NO. | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION | |
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| | | | | | | YES | NO |
| O | | | | | | | |
| P | | | | | | | |
| Q | | | | | | | |

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| | DOCUMENT (Including Author, Title, Source, and Pertinent Pages) | DATE |
| R | "Challenges in High Yield, Fine Pitch Solder Ball Attachment", by Ivy Qin, et al., SEMI - Semicon Singapore Semiconductor Packaging Conference, pp. 1-10 | 05/2001 |
| S | | |
| T | | |
| EXAMINER | DATE CONSIDERED 9/13/04 | |

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

U.S. PATENT AND TRADEMARK OFFICE